

**Previous lecture**

- Atomistic models for diffusion coefficients - ionic crystals
  - Intrinsic and extrinsic regimes in stoichiometric material
- Diffusion in nonstoichiometric oxides; the oxygen sensor

**Today**

- Quick primer on grain boundary structure
- Diffusion spectrum in defective crystals
- Diffusion regimes in defective crystals
- DIGM (“dig-em”)

- Essentials of grain boundary structure

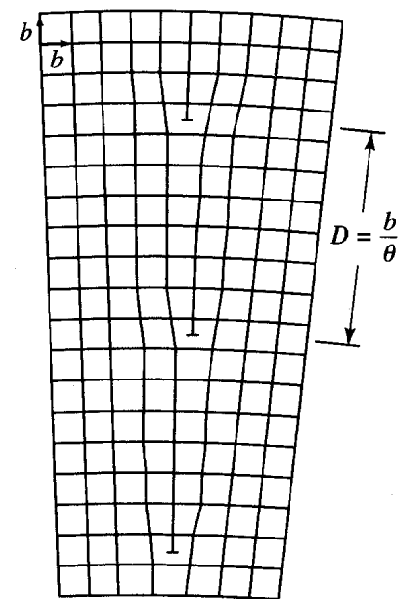
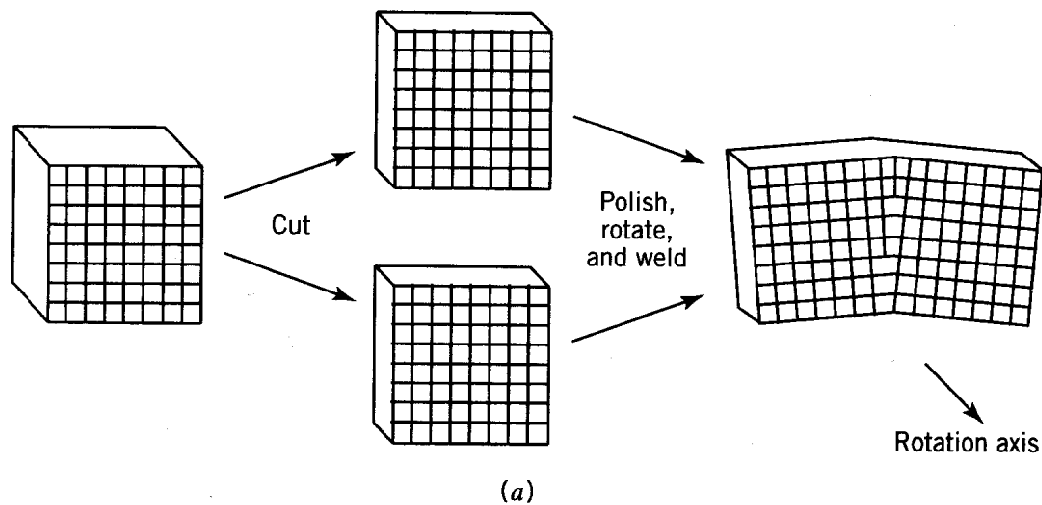
Specification of a grain boundary: five degrees of freedom (at least)

Rotation axis  $\hat{r}$

Rotation angle

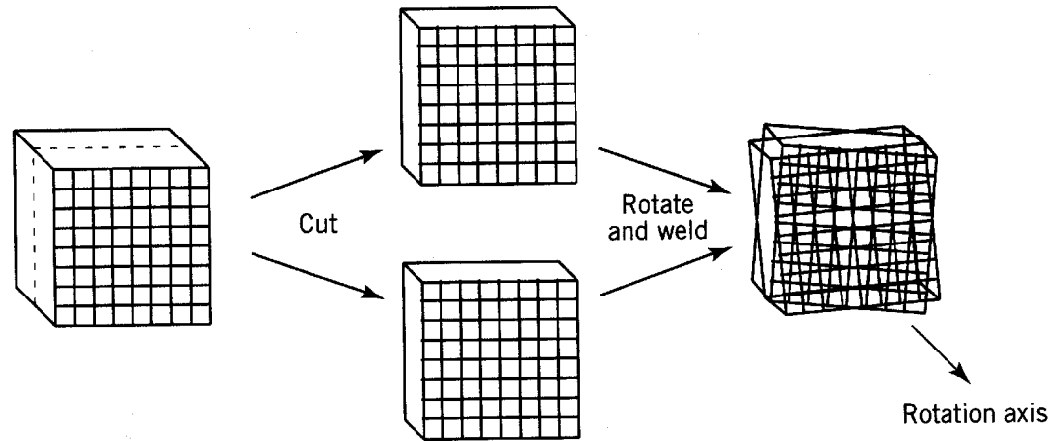
Boundary normal  $\hat{n}$

Example: tilt boundary

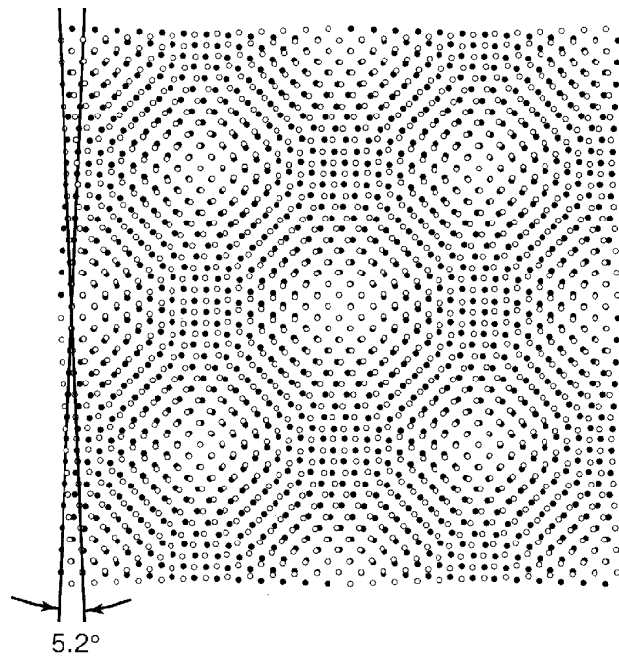


- Essentials of grain boundary structure

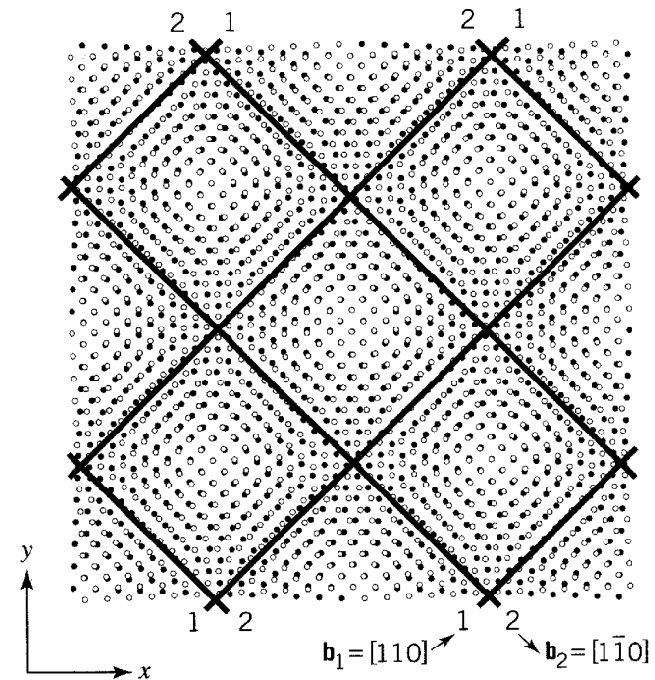
Example: twist boundary



Unrelaxed atom positions



Relaxed atom positions



## • Possible diffusion paths in polycrystals

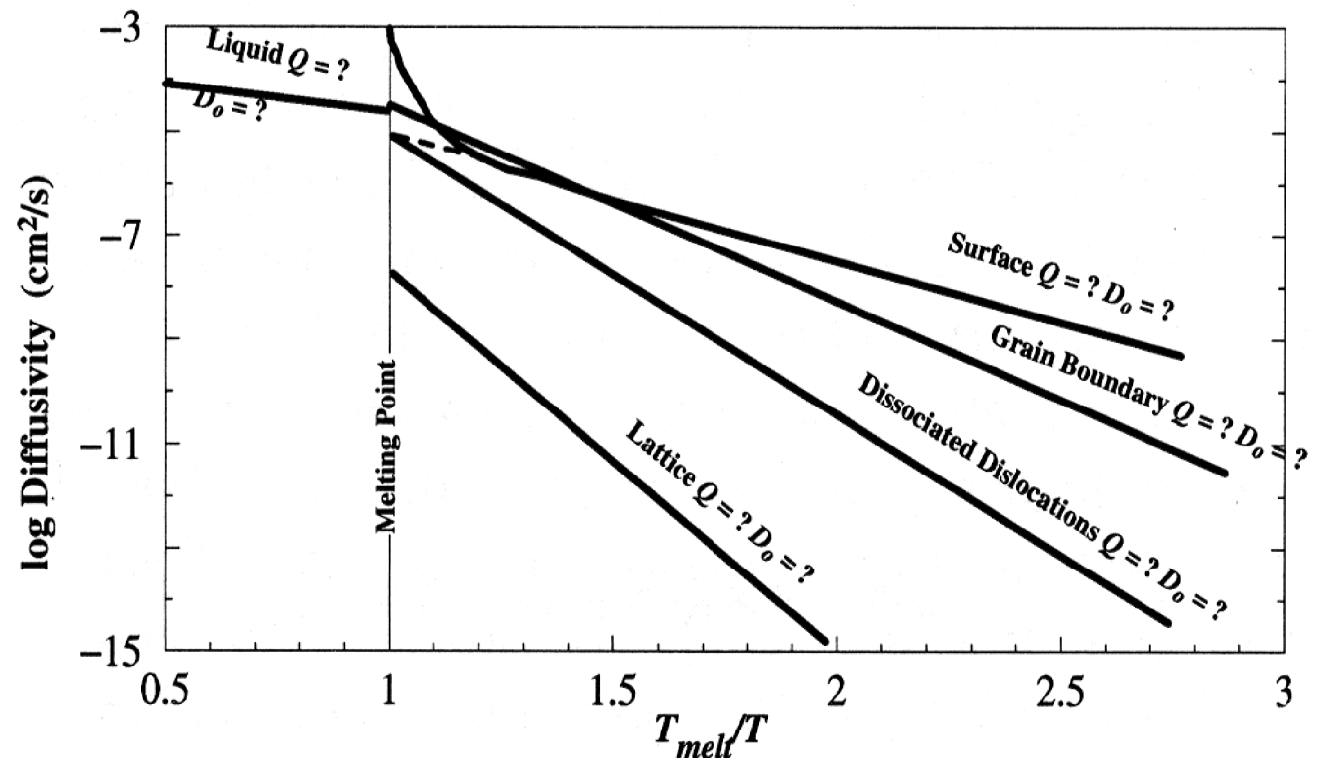
$D^{Bulk}$ , bulk (lattice) diffusivity

$D^{Bound}$ , grain boundary diffusivity

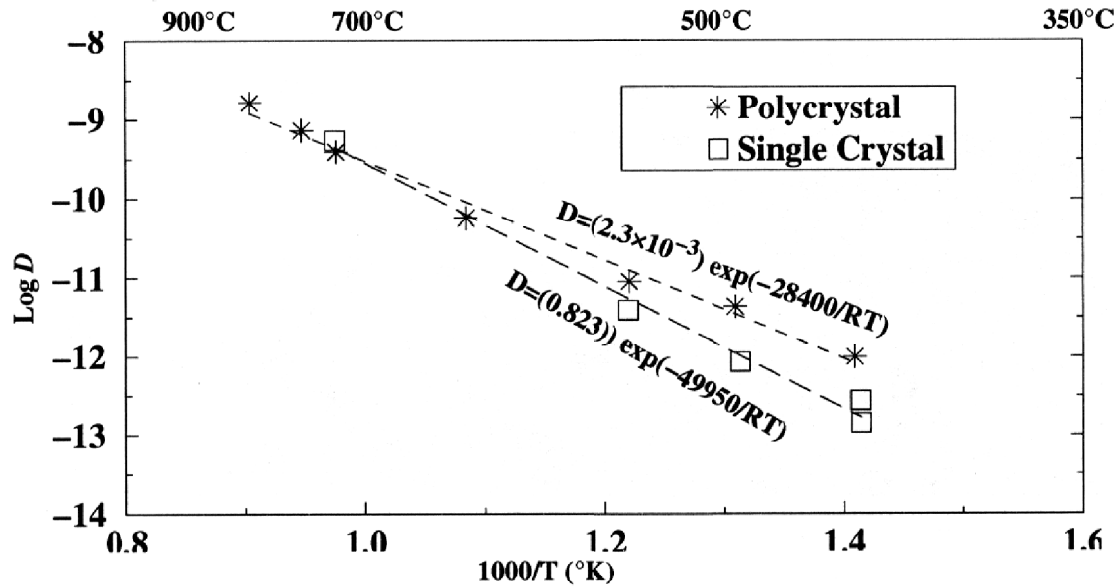
$D^{Surf}$ , (free) surface diffusivity

$D^{Disl}$ , dislocation diffusivity

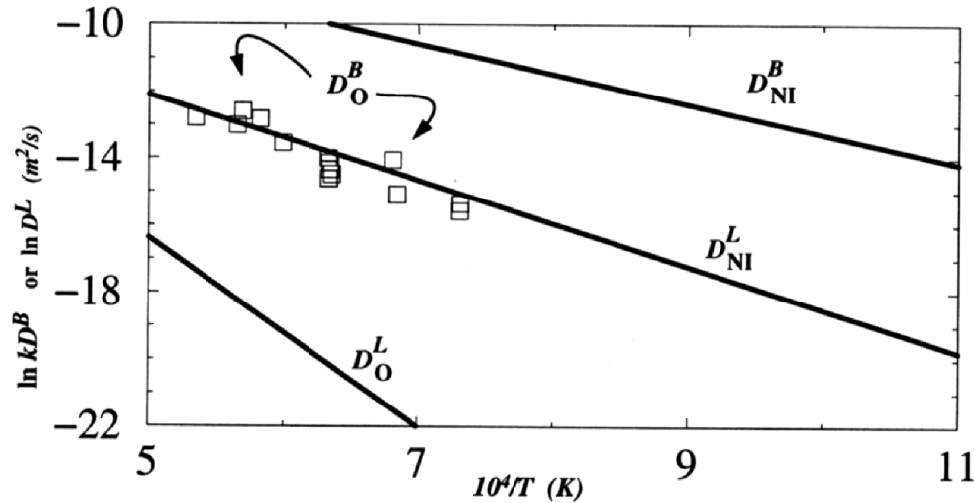
Typical behavior  
in fcc metals



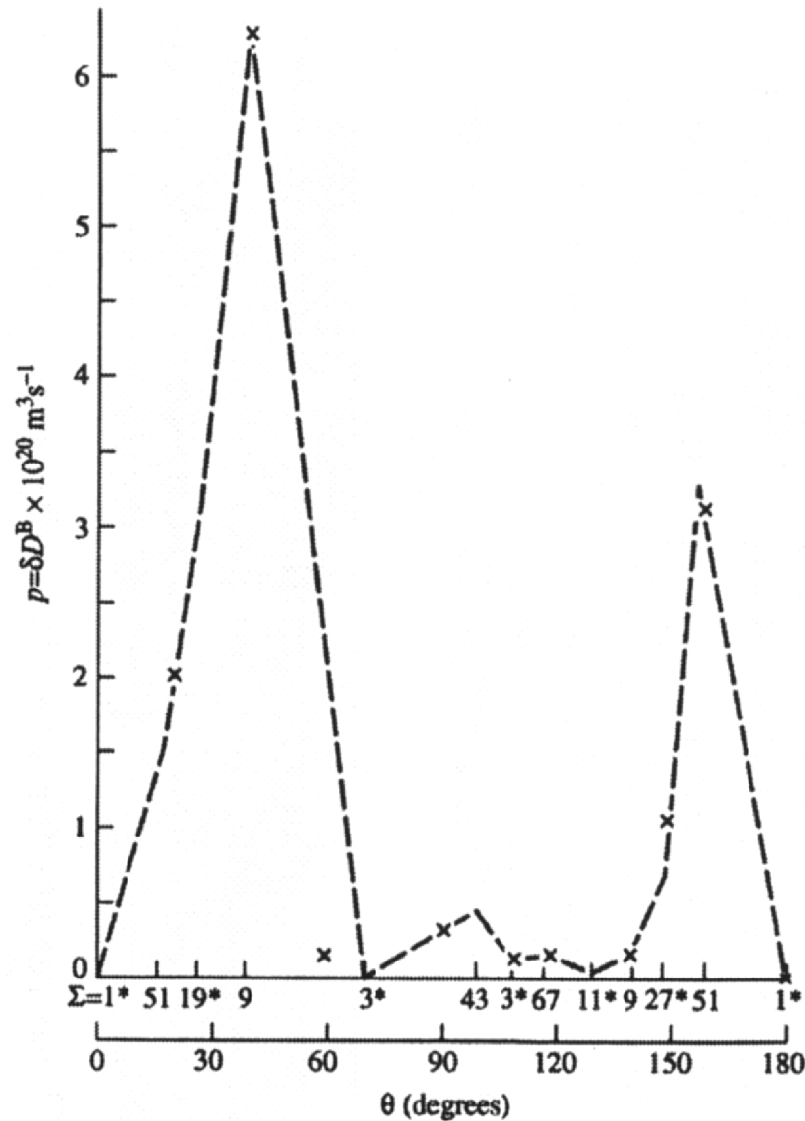
**In Silver**



**Diffusion data from NiO, comparing rates of bulk diffusion and grain boundary diffusion**



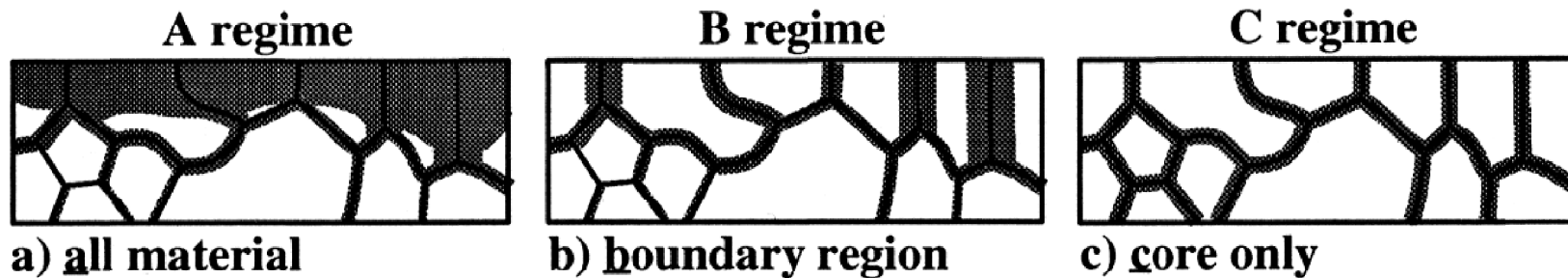
## Role of grain boundary structure on impurity diffusion



**Figure 9.2** Fit of idealized structural unit model to data of Herbeuval and Biscondi (1974) for the diffusion of Zn along the tilt axes [110] symmetric tilt boundaries in Al as a function of tilt angle,  $\theta$ . The delimiting boundaries chosen are indicated by asterisks, and, from left to right, are  $1^*(110)$ ,  $19^*(331)$ ,  $3^*(111)$ ,  $11^*(113)$ ,  $27^*(115)$ , and  $1^*(001)$ .

## Regimes of grain boundary “short-circuit” diffusion for stationary boundaries

Diffusing species initially coats top surface...



**Case A:** Characteristic diffusion distance in bulk  $>$  grain size  $s$ .

fraction of atomic sites in grain boundaries is  $3/s$

and effective mean squared displacement is  $D_{eff}t = D^L(1 - )t + D^B t$

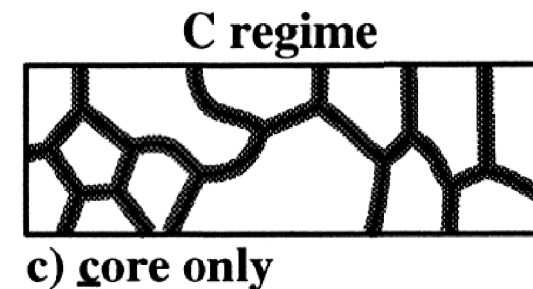
and for  $\ll 1$ ,  $D_{eff} = D^L + (3/s)D^B$

- “Multiple” because diffusing atom visits several grains

• Regimes of grain boundary “short-circuit” diffusion for stationary boundaries (continued)

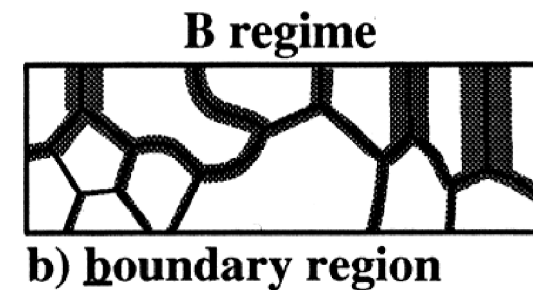
**Case C:** Characteristic diffusion distance in bulk  $<$  atomic spacing  $<$  characteristic diffusion distance in grain boundary.

- “Isolated” because a diffusing atom visits only the grain boundaries



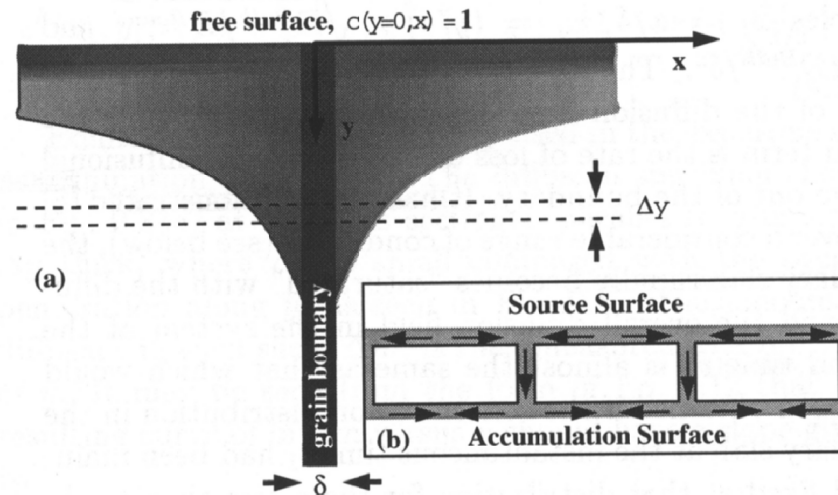
**Case B:** Intermediate regime where  $s^2 < D^{Bulk} t < s^2$

- “Isolated” because a diffusing atom visits only a single grain





## • Analysis of Type-B regime for Stationary Boundaries



Solve two-dimensional diffusion problem for fast boundary diffusion and relatively slow bulk diffusion, with constant concentration of diffusant at the surface as illustrated.

$$\frac{c^B}{t} = \frac{2c^B}{y_1^2} + 2 \frac{c^L}{x_1} \quad x_1=0$$

$$\text{with } x_1 = x/ \quad , \quad y_1 = (y/ ) \sqrt{D^{Bulk} / D^{Bound}} \quad , \quad \text{and } t_1 = D^{Bulk} t / \quad ^2$$

- **Analysis of Type-B regime for Stationary Boundaries (continued)**

For wide range of conditions

- g.b. acts like a source with erf solution off to the sides

$$c^L(x_1, y_1, t_1) = 0 = c^B(y_1, t_1) \left[ 1 - \operatorname{erf} \frac{x_1}{2\sqrt{t_1}} \right]$$

- g.b is effectively “saturated” and steady-state solution to diffusion equation applies in the boundary

$$\frac{c^B}{t} = 0 = \frac{2c^B(y_1, t_1)}{y_1^2} - 2c^B(y_1, t_1) \frac{1}{x_1} \operatorname{erf} \frac{x_1}{2\sqrt{t_1}} \quad x_1=0$$

and thus

$$c^B(y_1, t_1) = \exp - \frac{4}{t_1}^{1/4} y_1$$

and so the final solution is

$$c^L(x_1, y_1, t_1) = \exp - \frac{4}{t_1}^{1/4} y_1 \left[ 1 - \operatorname{erf} \frac{x_1}{2\sqrt{t_1}} \right]$$

## References for additional study:

### **KPIM Chapter 9**

### **KPIM Appendix B, Structure of Interfaces Involving Crystalline Materials (background on structure)**

### **Allen and Thomas, *The Structure of Materials*, 1999**

#### **Section 5.3, Surface Imperfections (background on grain boundaries, stacking faults, etc.)**

### **R W Balluffi and A Sutton, *Interfaces in Crystalline Materials*, 1995**

#### **Chapter 8 on Diffusion at Interfaces - goes into more advanced topics than KPIM**